



Final Product/Process Change Notification

Document #:FPCN22979X

Issue Date:04 Dec 2019

Title of Change:	Transfer of the Wafer level CSP Bump to Flip Chip International and dies sales to ON Semiconductor Seremban.
Proposed First Ship date:	11 Mar 2020 or earlier if approved by customer
Contact Information:	Contact your local ON Semiconductor Sales Office or <Steve.Frost@onsemi.com>
PCN Samples Contact:	Contact your local ON Semiconductor Sales Office or <PCN.samples@onsemi.com>. Sample requests are to be submitted no later than 30 days from the date of first notification, Initial PCN or Final PCN, for this change. Samples delivery timing will be subject to request date, sample quantity and special customer packing/label requirements.
Additional Reliability Data:	Contact your local ON Semiconductor Sales Office or Chielo.Basa@onsemi.com
Type of Notification:	This is a Final Product/Process Change Notification (FPCN) sent to customers. FPCNs are issued 90 days prior to implementation of the change. ON Semiconductor will consider this change accepted, unless an inquiry is made in writing within 30 days of delivery of this notice. To do so, contact PCN.Support@onsemi.com
Marking of Parts/ Traceability of Change:	Tracecode F(YW)
Change Category:	Assembly Change, WLCPS Bump site change
Change Sub-Category(s):	Manufacturing Site Transfer

Sites Affected:

ON Semiconductor Sites	External Foundry/Subcon Sites
ON Semiconductor Seremban, Malaysia	Deca Technologies, Philippines
	Flipchip International, USA

Description and Purpose:Manufacturing Site transfer

ON Semiconductor would like to inform its customers of the intention to transfer the Bumping, Saw and TnR processes from Deca Technologies to Flip Chip International (FCI) for Bump and On Semiconductor Seremban, Malaysia for Die sales Saw & TnR.

The effected devices listed in this document are currently bumped, sawn & TnR at Deca. Upon approval of the final PCN, the effect devices may be bumped, Sawn and TnR at either Deca (until supply is depleted) or at FCI for Bump and Seremban, Malaysia for saw and TnR as shown in the table below.

	Before Change Description	After Change Description
Wafer Bump	Deca Technologies	Flip Chip International
Die Sales (Saw & TnR)	Deca Technologies	ON Semiconductor Seremban, Malaysia

There are no product material changes as a result of this change

	From	To
Product marking change	Tracecode d (YW)	Tracecode F(YW)

There is no change to product identification. Only to assembly site code.

YW= two digit year and work week date code

**Reliability Data Summary:**

QV DEVICE NAME: NCP6335/6336

RMS# : S40230, S47529, S45146

PACKAGE : FCDCA

Test	Specification	Condition	Interval	Results
HTOL	JESD22-A108	Ta= 125°C	168hrs	0/231
HTSL	JESD22-A103	Ta= 150°C	168hrs	0/231
TC	JESD22-A104	Ta= -40°C to + 125°C	500 cyc	0/231
uHAST	JESD22-A118	130°C, 85% RH, 18.8psig, unbiased	96 hrs	0/231

Electrical Characteristics Summary:

Electrical characteristics are not impacted.

List of Affected Parts:

Note: Only the standard (off the shelf) part numbers are listed in the parts list. Any custom parts affected by this PCN are shown in the customer specific PCN addendum in the PCN email notification, or on the **PCN Customized Portal**.

Part Number	Qualification Vehicle
NCP6360FCCT2G	NCP6335



Appendix A: Changed Products

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Product	Customer Part Number	Qualification Vehicle	New Part Number	Replacement Supplier
NCP6360FCCT2G		NCP6335		